

<b>Notice of References Cited</b>	Application/Control No. 10/802,653	Applicant(s)/Patent Under Reexamination EISENSCHMID ET AL.	
	Examiner David A. Rogers	Art Unit 2856	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-4,241,384	12-1980	Diziere, Bernard	362/203
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
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	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

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	N					
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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	"Molded Interconnect Devices Reshape Electromechanical Design", September 2000, available on the Internet at < <a href="http://www.elecdesign.com">http://www.elecdesign.com</a> >.
	V	
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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